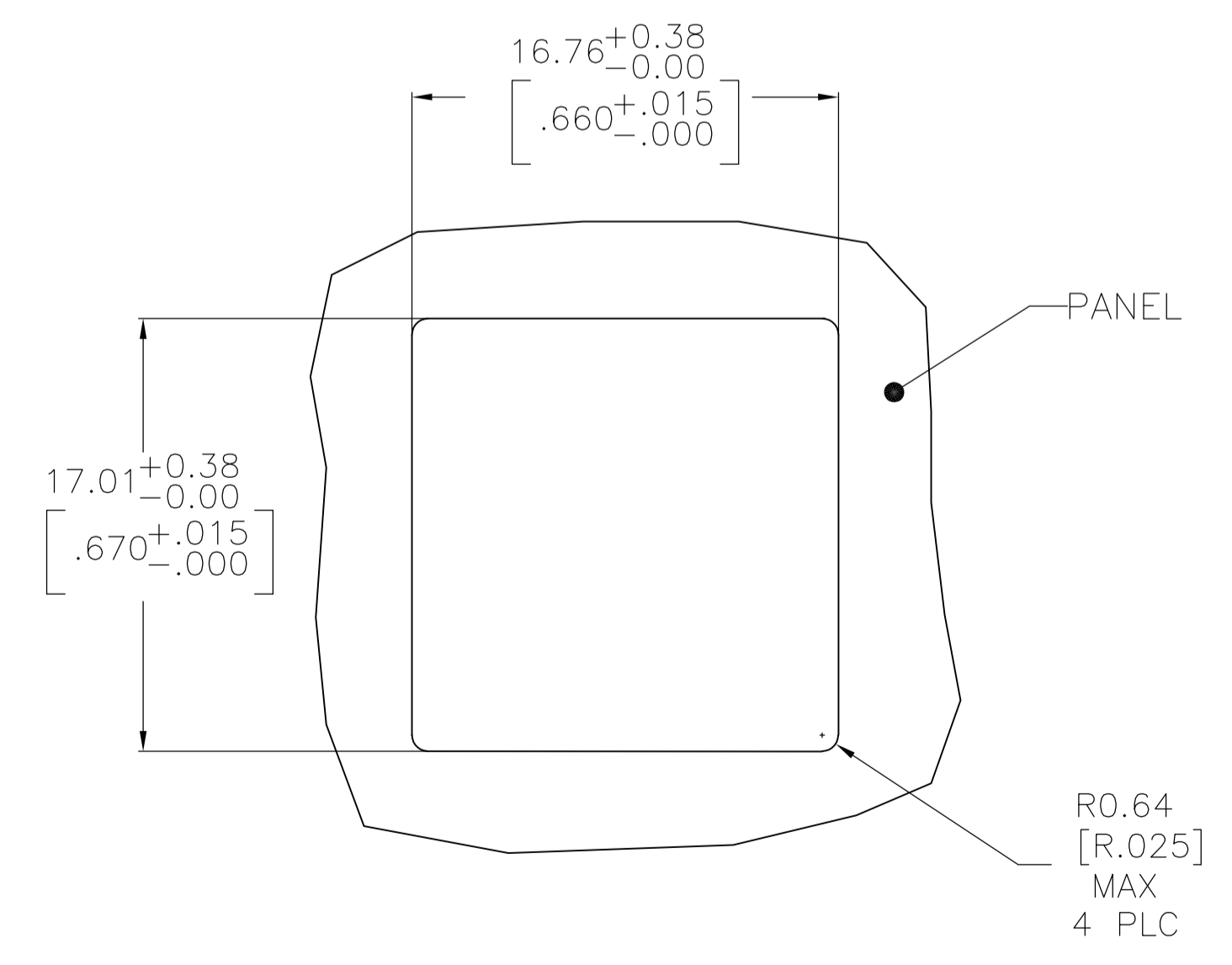


RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

- MATERIAL:
 HOUSING – POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS – 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
 SHIELD – COPPER ZINC ALLOY PLATED WITH 3.0µm[.000120] MIN THICK REFLOWED TIN.

2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

6368115-1
PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN	L. VARELA - DOCKS	15JUN2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608		
DIMENSIONS: mm [INCHES]		CHK	J. WESTMAN	15JUN2005	NAME MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, SHIELDED, WITH PANEL STOPS, PCB AND PANEL GROUNDS (IR COMPATIBLE)		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	S. FLICKINGER	15JUN2005	PRODUCT SPEC 108-1163		
0 PLC ± -		APPLICATION SPEC		114-2048		SIZE	CAGE CODE
1 PLC ± -		WEIGHT		A1 00779		SCALE	4:1
2 PLC ± -		CUSTOMER DRAWING		6368115		SHEET	1 OF 1
3 PLC ± 0.13(.005)		SCALE		4:1		REV	C
4 PLC ± -		SHEET		1 OF 1		REV	
ANGLES ± -		REV		C			